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Dated: June 2, 2009

Electronic Signature for James E. Armstrong, IV: /James E. Armstrong, IV/

Docket No.: 80428(302761)
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Kunihiro Kakihara et al.

Application No.: 10/561,966

Confirmation No.: 1627

Filed: December 22, 2005

Art Unit: 1792

For: RESIN PLATING METHOD WITH ADDED
HEAT-TREATING PROCESS

Examiner: N. T. Leong

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir/Madam:

INTRODUCTORY COMMENTS

In response to the Office Action dated February 2, 2009, please amend the above-identified U.S. patent application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks begin on page 5 of this paper.